Background

Metamaterials are artificial media exhibiting advantageous and unconventional physical/mechanical properties that are not readily found in nature. These artificial materials are composed of a microscale engineered arrangement of structural elements that, albeit being made of conventional materials, lead to unusual responses. They have a foundation in electromagnetics, but have recently found widely innovative applications in several disciplines like antenna engineering, quantum optics, materials science, mechanics, acoustics, energy transfer, and medicine. Metamaterials are not only an active and growing research subject, but are also finding their way to commercialization. The international congress Metamaterials'2023 is dedicated to providing a platform for scientists from all over the world to share their research and innovations in the multidisciplinary area of metamaterials.

Aim and Scope of the Themed Issue

The aim of this special issue of the Metamaterials'2023 congress is to provide a representative collection of recent developments in microwave, optical, photonic, and mechanical metamaterials, offering the possibility to extend in a journal paper the best contributions submitted and presented at Metamaterials'2023. We, therefore, are excited to invite metamaterials researchers to submit an extended version of their work presented at the conference.

Submissions

All relevant papers will be carefully considered, vetted by a distinguished team of international experts, and published in accordance to the **Journal's standard policies**. Full research papers and comprehensive review articles can be submitted online via the journal's submission and peer review site**.**
Instructions for Authors at**:** **https://epjam.edp-open.org/author-information/instructions-for-authors**

Article Processing Charges

For accepted articles submitted in 2023, the journal uses the Liberty APC model, a 'Pay What You Want' model whereby authors can choose their own fair price to publish an article in Open Access. This allows authors to publish regardless of their level of funding. Authors can select the amount that they will pay on acceptance of their article beginning from 500 €.
The journal does not have any submission fee.

- *Special discount concerning this Special Issue*

For this Special Issue, an exceptional Article Processing charge is proposed: Authors can select the amount that they will pay on acceptance of their article beginning from 0€ instead of 500 €. In this way, Authors who have the possibility and want to contribute to the development of the journal, will be able to pay what they want (and is possible for them).

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Submission deadline – September 30th 2023

Article submission and editorial system **here**.

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